2020 Interim Results Announcement

29 July 2020
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Awards & Accolades

Forbes Asia — 2019 —
BEST OVER A BILLION

2019 HKMA Quality Award

GRAND AWARD

SINGAPORE QUALITY AWARD
2019 WINNER

Winner of the productronica Innovation Award 2019

Best Companies Poll 2019 ASIAMONEY

ASM Pacific Technology
The World’s Technology & Market Leader

Q2 2020 Group Revenue: USD 557m
ASMPT’S Major Facilities Around The World

- Sales Offices
- Business Centre / R&D / Manufacturing Site

- Hong Kong
- Beuningen
- Boston
- Porto
- Munich
- Regensburg
- Fuyong (福永)
- Huizhou (惠州)
- Longgang (龙岗)
- Taoyuan
- Singapore
- Longgang (龙岗)
- Johor
- Huizhou (惠州)
- Weymouth
- Porto

>2,000 Global R&D staff
>1,400 Patents on leading edge technologies
10 R&D centres worldwide
12 Manufacturing facilities
Three Business Segments With Leading Market Positions

**SMT SOLUTIONS**

1. **#2 in SMT Equipment Market**
   - 2019 Worldwide SMT Market Share:
     - ~22%

**MATERIALS**

1. **#3 in Leadframe Market**
   - 2018 Worldwide Leadframe Market Share:
     - ~9%

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*Sources: VLSI, SEMI and ASMPT Market Intelligence*
Our Strategic Value-added Acquisitions

Advanced Packaging
- Largest installed base of panel deposition tools
- Addition to the Advanced Packaging suite of solutions
- High Performance Computing (HPC)

Silicon Photonics
- Ultra high precision sub-micron die attach equipment solutions
- In prime position to capture demand for future data centre bandwidth growth and next generation 5G deployments

Manufacturing Execution Software
- Provider of automation and manufacturing software for high-tech industries
- Capture demand for SMART Factory software solutions
- Well-established MES solutions provider with a strong presence in China.
- Complements Critical Manufacturing MES solutions, reinforcing ASMPT’s position in the China market.
Our Participation in Emerging and Disruptive Technologies

Minority Investments in Start-ups

- X-ray Inspection
  - X-ray inspection of advanced semiconductor packages
  - Up to 100X faster vs conventional X-ray using proprietary technology

- 3D Laser Printing
  - Israeli company with cutting-edge technology
  - Potentially disruptive technology to the SMT printing industry

Strategic Collaborations

- Data Analytics
  - Industrial IoT Solutions to deliver holistic data analytics solutions
  - Provide customer value through productivity, quality and reliability in manufacturing operations

- AI Chip Technology
  - Development of Heterogeneous Integration (HI) to advance packaging technologies and tools

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**X-ray Inspection**

- Israeli company with cutting-edge technology
- Potentially disruptive technology to the SMT printing industry
- Up to 100X faster vs conventional X-ray using proprietary technology

**3D Laser Printing**

- Development of innovative 3D printing solutions
- Enhancements in productivity and accuracy

**Data Analytics**

- Industrial IoT Solutions for improved data analysis
- Holistic solutions for decision-making

**AI Chip Technology**

- Development of cutting-edge AI technologies
- Advancements in packaging technologies

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**Customer Value**

- Increased productivity
- Improved quality and reliability
- Enhanced decision-making capabilities
2020 Q2 Highlights
# Q2/1H 2020 Billings

## Group Billings
- **1H Group Billings** ~US$1B
  - ▲ 5.9% YoY  ▼ 10.5% HoH
- **Q2 Group Billings**  
  - ▲ 19.5% YoY ▲ 27.8% QoQ

## SEMI
**Key drivers for Q2 YoY billings growth**
- **Advanced Packaging**  
  - NEXX delivered strong growth
- **Other drivers:** Optoelectronics and IC/Discrete
- **Traditional wire/die bonders** delivered relatively strong growth
- **CIS billings** relatively weaker due to soft smartphone market demand

## SMT
- Driven by 5G & SiP applications

<table>
<thead>
<tr>
<th></th>
<th>Q2</th>
<th>1H</th>
<th></th>
<th></th>
<th></th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>USD</td>
<td>QoQ</td>
<td>YoY</td>
<td>USD</td>
<td>HoH</td>
<td>YoY</td>
</tr>
<tr>
<td><strong>Group</strong></td>
<td>557m</td>
<td>+27.8%</td>
<td>+19.5%</td>
<td>992m</td>
<td>-10.5%</td>
<td>+5.9%</td>
</tr>
<tr>
<td><strong>Semi Solutions Segment</strong></td>
<td>279m</td>
<td>+43.0%</td>
<td>+33.8%</td>
<td>473m</td>
<td>-4.5%</td>
<td>+16.6%</td>
</tr>
<tr>
<td><strong>Materials Segment</strong></td>
<td>74m</td>
<td>+43.2%</td>
<td>+28.2%</td>
<td>126m</td>
<td>-3.2%</td>
<td>+15.6%</td>
</tr>
<tr>
<td><strong>SMT Solutions Segment</strong></td>
<td>204m</td>
<td>+8.0%</td>
<td>+2.2%</td>
<td>393m</td>
<td>-18.7%</td>
<td>-6.9%</td>
</tr>
</tbody>
</table>
Q2 2020 Billings – Business Segments

QoQ Growth:
+43.0%

QoQ Growth:
+8.0%

QoQ Growth:
+43.2%

Semiconductor Solutions (USD'M)

SMT (USD'M)

Materials (USD'M)
### Q2/1H 2020 Group Bookings

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<td><strong>SMT Solutions Segment</strong></td>
<td>167m</td>
<td>-38.4%</td>
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**Group**
- 1H Bookings ▲ HoH and YoY
- Q2 Bookings ▼ QoQ and YoY as a result of overall weak sentiment due to COVID-19

**SEMI**
- Q2 Bookings ▼ QoQ due to higher Q1 base
- Key drivers of Q2 Bookings
  - Advanced Packaging
  - Optoelectronics and IC/Discrete
- Q2 Bookings for CIS relatively weaker due to soft smartphone market

**SMT**
- Key driver of Q2 Bookings
  - 5G-related investments in China
  - SiP
- Q2 Bookings in Automotive and Industrial Applications were weak

**Materials**
- Q2 Bookings at high level despite decline QoQ after 5 consecutive quarters’ growth
Q2 2020 Bookings – Business Segments

QoQ Growth: -26.7%

Semiconductor Solutions (USD'M)

QoQ Growth: -38.4%

SMT (USD'M)

QoQ Growth: -11.8%

Materials (USD'M)
## Q2/1H 2020 Group GM & Profitability

<table>
<thead>
<tr>
<th>Gross Margin</th>
<th>1H</th>
<th>HoH</th>
<th>YoY</th>
<th>Q2</th>
<th>QoQ</th>
<th>YoY</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Group</strong></td>
<td>34.5%</td>
<td>-29 bps</td>
<td>-34 bps</td>
<td>35.2%</td>
<td>+169 bps</td>
<td>-54 bps</td>
</tr>
<tr>
<td><strong>Semi Solutions Segment</strong></td>
<td>42.2%</td>
<td>+16 bps</td>
<td>+219 bps</td>
<td>42.9%</td>
<td>+162 bps</td>
<td>+211 bps</td>
</tr>
<tr>
<td><strong>Materials Segment</strong></td>
<td>13.5%</td>
<td>+409 bps</td>
<td>+250 bps</td>
<td>16.9%</td>
<td>+838 bps</td>
<td>+546 bps</td>
</tr>
<tr>
<td><strong>SMT Solutions Segment</strong></td>
<td>31.8%</td>
<td>-225 bps</td>
<td>-409 bps</td>
<td>31.3%</td>
<td>-101 bps</td>
<td>-616 bps</td>
</tr>
<tr>
<td><strong>Group Billing (USD)</strong></td>
<td>992m</td>
<td>-10.5%</td>
<td>+5.9%</td>
<td>557m</td>
<td>+27.8%</td>
<td>+19.5%</td>
</tr>
<tr>
<td><strong>Operating Profit (HKD)</strong></td>
<td>641m</td>
<td>-16.7%</td>
<td>+30.2%</td>
<td>496m</td>
<td>+241.1%</td>
<td>+95.8%</td>
</tr>
<tr>
<td><strong>Net Profit (HKD)</strong></td>
<td>391m</td>
<td>-12.0%</td>
<td>+119.2%</td>
<td>365m</td>
<td>+1,341.5%</td>
<td>+421.8%</td>
</tr>
</tbody>
</table>

### Group
- Q2 Group GM close to mid-point of guidance
- Q2 Group Billing, Operating Profit and Net Profit ▲ QoQ and YoY

### SEMI
- 1H GM ▲ YoY due to higher volume effect, increased productivity, product mix and cost reduction efforts

### SMT
- 1H GM ▼ YoY due to lower contribution from Automotive and Industrial Applications; and larger China customer base

### Materials
- 1H GM ▲ YoY due to higher volume effect and discontinuation of loss-making MIS business
Key Highlights:

Semiconductor Solutions Segment

- Strong global demand for HPC for datacentre and 5G applications
  - Q2 Billings growth YoY underpinned by Advanced Packaging
  - Q2 NEXX Bookings ▲ ~100% YoY
- Largest installed base to-date worldwide for Thermo-Compression Bonding (TCB) solutions
- NEXX has largest installation of panel plating tools for HPC applications
- Frontier-focused joint development with IBM Research on integrated solutions for HI, using ALSI Laser dicing, Hybrid Bonding and other AP interconnect tools
1H YoY Bookings Growth: -10.3%

Key Highlights:

SMT Segment

- Market leader in System-in-Packaging (SiP)
- 1H booking momentum driven by
  - 5G-related investments
  - SiP – fast growing business within SMT
Key Highlights:

**Materials Segment**

- Segment new bookings increased five out of the last six quarters
- GM improvements resulted from higher volume effect and discontinuation of loss-making MIS business
- High level of Q2 Bookings indicates healthy demand for semiconductor devices
- Strategic JV expected to bring Materials Business to greater heights
R&D Commitment Makes Us a Preferred Partner of Choice

USD1,742 million invested in R&D

1H 2020 R&D expenditure

- US$ 101 million
- 11.7% of Equipment Sales

R&D expenditure (USD million)

Package Interconnection
Optics precision engineering
Vibration control
Laser dicing & grooving
SMT

11.7%
An Extensive Customer Base

- No single customer accounted for more than 10% of Group revenue
- Top 5 customers accounted for 16.25% of Group’s 1H 2020 revenue
- Top 20 customers include:
  - World’s leading Telecommunication and Information Technology provider
  - Leading High-Density Substrate makers
  - World’s leading IDMs
  - Tier 1 OSATs, major OSATs in China
  - Major camera module makers
  - Top EMS providers
  - Leading automotive component suppliers
- Among Top 20 customers of Group:
  - 4 from SMT Solutions segment
  - 8 from both Semi Solutions & SMT Solutions segment

China Leads Market Recovery

1H 2020 Geographical Distribution of Revenue

- China, 50.5%
- Americas, 8.4%
- Malaysia, 5.1%
- Japan, 4.4%
- Korea, 3.0%
- Thailand, 2.8%
- Vietnam, 1.7%
- Philippines, 1.6%
- India, 0.2%
- Others, 1.1%
- Taiwan, 8.6%
- Europe, 12.6%
1H 2020 Revenue Breakdown by Application Markets

1H 2020 Billing by Market Application

More Resilient in a Downturn with Multiple Application Markets Strategy
1H2020 Dividends

- Adopting a prudent stance in light of COVID-19 outbreak situation
- Dividend of HKD 0.70 for 1H20, representing a payout ratio of 74% for 1H20
New Lifestyle Norms

Fast-tracking Digitalisation

“Zoom, Microsoft Teams usage are rocketing”
*Marketwatch, April 2020*

“First-Quarter Demand Picked Up on Laptop Orders”
*Intel*

“Apple and Google partner on COVID-19 contact tracing technology”
*Apple, Google, April 2020*

‘Work from Home’ Initiatives by Companies Worldwide

Home-based Learning adopted by schools

Online “Live” Fitness Classes

Harnessing Technology in Contact Tracing
Data-Centric Era will spur Semiconductor Demand

**Collect**
Camera, 3D Sensing, Industry IoT, Sensor, LIDAR

**Transmit**
5G, WiFi, LiFi

**Store**
Big Data Centre, Cloud Computing, Memory

**Analyse**
AI, TPU, Data Analytics, HPC

**Visualise**
AR, VR, Micro LED, Mini LED

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**ASMPT’s Enabling Solutions**

**Collect**
- CMOS Imaging Sensors
- Active Alignment
- Precision Die Attach

**Transmit**
- Silicon Photonics
- RF Filters
- Wire Bonding
- SAW Filters
- BAW Filters
- SMT Solutions
- PVD

**Store**
- Silicon Photonics
- TCB
- Wire Bonding
- PLFO
- Laser Dicing

**Analyse**
- WLFO
- PLFO
- Pick & Place
- Laser Grooving
- TCB
- PVD/ECD
- Precision Die Attach
- Heterogeneous Integration

**Visualise**
- High Precision Die Attach
- Mini/Micro LED Displays
Q2 2020
Growth Drivers For ASMPT

Advanced Packaging
China Supply Chain Localisation
5G
Optoelectronics

APPLICATIONS
Digital Acceleration Opportunities in China

China’s investment in 5G infrastructure

Investment (in billions of yuan)

<table>
<thead>
<tr>
<th>Company</th>
<th>2019</th>
<th>'20</th>
</tr>
</thead>
<tbody>
<tr>
<td>China Mobile</td>
<td>250,000</td>
<td></td>
</tr>
<tr>
<td>China Unicom</td>
<td>110,000</td>
<td></td>
</tr>
<tr>
<td>China Telecom</td>
<td>140,000</td>
<td></td>
</tr>
</tbody>
</table>

Planned number of base stations*

*Source: Trendforce and Nikkei Asian Review reporting
5G Will Transform the World Beyond Our Imagination

Infrastructure

- **2019-2025: 25-30mil New 5G Base Stations**
  
  Source: Topology Research Institute 2019

- **2023: 417mil New 5G Handsets**
  
  Source: IDC, 2019

Terminal

- **50 MEMS & Sensors per car**
  
  Source: Bosch, 2019

Big Data Cloud Servers

- **“Power” Up All Industries**

Smart Consumer

- **5G Will Transform the World Beyond Our Imagination**

Automotive

ASMPT Solutions for 5G:

- **Photonics Solutions**
- **IC & Discrete Solutions**
- **Image Sensor Solutions**
- **Advanced Packaging**
- **SMT Solutions**
- **Power Solutions**
- **Wafer Separation**
Complete CIS Camera Assembly Solution

Market Leader for Unique In-line Solutions

IDEALine™
(CMOS Image Sensor Solution)

ACamLine™
(Automotive Camera Assembly Solution)

AUTOPIA FT
(Automatic Camera Testing System)

Smartphone Solutions

Automotive Solutions
Advanced Packaging
Enables Heterogeneous Integration

End Applications:

**DATACENTRES**
for HPC, Machine Learning

**IoT ERA**
Smart Wearables & Smart Machines (Factories)

**AUTOMOTIVE**
Sensors, Camera, Body Electronics, Safety Systems, Infotainment

**GPU**
for VR/AR & AI

**NEXX**
PVD | ECD Bumping, TSV & RDL

**NUCLEUS XPM**
HBM Bonder

**NUCLEUS**
Pick & Place Wafer & Panel Level

**LASER 1205**
Laser Separation Wafer-Dicing & Grooving

**FIREBIRD**
TCB, FLI

**ORCAS**
Compression mold Wafer & Panel Level
Hybrid Bonding Solution
Next Generation Heterogeneous Integration Technology

Bringing Heterogeneous Integration to the next level to enable high performance device, driving for future AI & HPC technology in a more cost effective way

- Higher Interconnect density
  Interconnect density > $10^5$/mm², with connecting pad size and pitch down below 5um

- Zero bond line with bump-less interconnect
  With direct Cu-Cu hybrid bonding

- Better signal integrity and thermal performance

ASM Advanced Packaging Technology enables Hybrid bonding solution for Heterogeneous Integration

- Ultra High Placement accuracy
  Bond accuracy +/-200nm

- Ultra High Cleanliness

- High Productivity
  CPH > 2K

Source: Chipworks
Source: Chipworks
Source: Xperi
Source: Xperi

ASM Pacific Technology
Future Growth Drivers for OPTO Business

**MiniLED**
*Medium to Large RGB / BLU Display*

- Market Size CAGR (2019 – 2025) ~ 35%

**MicroLED**
*Small Gadget & Transparent Display*

- Market Size CAGR (2019 – 2025) ~ 131%

**Fast Growing Applications**

- **Automotive Display CAGR (2019 – 2025)**: 63%
- **Digital Display CAGR (2019 – 2025)**: 35%
- **Large Display CAGR (2019 – 2025)**: 31%

- **Smartphone Display CAGR (2022 – 2025)**: 118%
- **Wearable Display CAGR (2020 – 2025)**: 91%
- **VR Display CAGR (2021 – 2025)**: 75%

**Source:** LEDInside, Sep 2019
Unique and Ready for Mass Production
Mini & Micro LED Solution

MASS TRANSFER
Up to 300,000 chips per bonding cycle
Booming Applications in Photonics Market

Si Photonics Market Size (USD'M)

- Datacenter transceivers
- Long haul transceivers
- Optical interconnects
- Automotive LiDAR
- Immunoassay tests
- Fiber-optic gyroscope
- 5G transceivers

2019
$480M

$117M
$22M
$44M
$18M
$20M

CAGR 40%

CAGR 46%

$3.6B

2025
$3.9B

$186M

CAGR 8%

Source: Yole, 2020
IIoT & Smart Manufacturing
Powered Up by 5G Network

Factory in Location A
Factory in Location C
Factory in Location B
Factory in Location D

Industrial IoT

~ 24% CAGR (2019 – 2023)
Source: Marketwatch, Sep 2019
Digital Technologies Enabling the Autonomous Driving Experience

5G NETWORK
MEMS
POWER
DISPLAY
Outlook
Outlook

- Global full year 2020 growth projections revised downwards from -3.0% to -4.9% by IMF during June 2020 review.
- Threat from a second wave of COVID-19 infection and continued fallout from the worsening US-China tension remains a global concern for 2H2020.
- In light of these uncertainties, no guidance on Q3 Bookings will be provided.

Q3 Group Billings Guidance
- US$480m – US$560m
- Subdued demand for Automotive and weakness in Eurozone

Longer Term Outlook
- Supply chain localization and deployment of 5G infrastructure opening up new market opportunities in:
  - AP, Silicon Photonics, IIoT, mini and micro LED solutions, Power semiconductor and Industry 4.0
Industry Growth Forecast (2020)

Semiconductor Industry

- Gartner, Apr-20: -0.9%
- Omdia, Apr-20: 2.5%
- IDC, May-20: -4.2%
- Cowan LRA Model, May-20: 7.6%
- Semiconductor Intelligence, May-20: -6.0%
- WSTS, Jun-20: 3.3%

Forecast Global Assembly & Packaging Equipment Market

- VLSI Assembly & Packaging Equipment (Jun-20): -22%, 22%, -16%, 13%, 26%, -3%, -32%, 11%
- SEMI Assembly & Packaging Equipment (Jul-20): -26%, 33%, -18%, 20%, 26%, 1.9%, -27%, 10%
### Recent Awards & Recognition

#### Top 10 Best Chip Making Equipment Suppliers of 2020

<table>
<thead>
<tr>
<th>Rank</th>
<th>Segment</th>
<th>Company</th>
<th>Rating</th>
<th>Stars</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>LARGE</td>
<td>ADVANTEST</td>
<td>9.56</td>
<td>★★★★★</td>
</tr>
<tr>
<td>2</td>
<td>LARGE</td>
<td>TERADYNE</td>
<td>9.46</td>
<td>★★★★★</td>
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<tr>
<td>3</td>
<td>LARGE</td>
<td>ASML</td>
<td>9.31</td>
<td>★★★★★</td>
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<td>4</td>
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<td>5</td>
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<td>KLA</td>
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<td>6</td>
<td>FOCUSED</td>
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<td>7</td>
<td>FOCUSED</td>
<td>Lam Research</td>
<td>8.21</td>
<td>★★★★★</td>
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<td>FOCUSED</td>
<td>Applied Materials</td>
<td>8.00</td>
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<tr>
<td>9</td>
<td>FOCUSED</td>
<td>Hitachi HighTech</td>
<td>7.64</td>
<td>★★★★★</td>
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#### What the Best Suppliers of 2020 Are Best At

- **ADVANTEST**
  - Recommend Supplier
  - Trust in Supplier
- **ASML**
  - Technical Leadership
  - Quality of Results
- **axcelis**
  - Field Engineering Support
  - Partnership
- **Canon**
  - Overall Value
  - Partnering
- **Cohu**
  - Recommend Supplier
  - Partnership
- **FormFactor**
  - Technical Leadership
  - Trust in Supplier
- **Hitachi High-Tech**
  - Uptime
  - Product Performance and Quality of Results
- **ASML**
  - Technical Leadership
  - Quality of Results
- **FormFactor**
  - Technical Leadership
  - Trust in Supplier
- **Hitachi High-Tech**
  - Uptime
  - Product Performance and Quality of Results
- **Nikon**
  - Overall Value
  - Support After Sales
- **Teradyne**
  - Recommend Supplier
  - Trust in Supplier
- **Canon**
  - Overall Value
  - Support After Sales
- **MagicLabs**
  - Application Support
  - Recommend Supplier
- **Suss Microtec**
  - Application Support
  - Trust in Supplier
Q2/1H 2020
Financial Highlights
### Q2/1H 2020 Group Bookings

**Quarterly Group Bookings (USD‘M)**

**QoQ Growth:**
-29.4%

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### Q2/1H 2020 Group Billings

**QoQ Growth:** +27.8%

#### Quarterly Group Billings (USD’M)

<table>
<thead>
<tr>
<th>Quarter</th>
<th>Q1 14</th>
<th>Q2 15</th>
<th>Q3 16</th>
<th>Q4 17</th>
<th>Q1 19</th>
<th>Q2 20</th>
</tr>
</thead>
<tbody>
<tr>
<td>Billings</td>
<td>200</td>
<td>400</td>
<td>600</td>
<td>800</td>
<td>1000</td>
<td>1200</td>
</tr>
</tbody>
</table>

#### Group Billings

<table>
<thead>
<tr>
<th></th>
<th>Q2 2020 Billings</th>
<th>1H 2020 Billings</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>USD</td>
<td>YoY</td>
</tr>
<tr>
<td>Group</td>
<td>557m</td>
<td>+19.5%</td>
</tr>
<tr>
<td>Semi Solutions Segment</td>
<td>279m</td>
<td>+33.8%</td>
</tr>
<tr>
<td>Materials Segment</td>
<td>74m</td>
<td>+28.2%</td>
</tr>
<tr>
<td>SMT Solutions Segment</td>
<td>204m</td>
<td>+2.2%</td>
</tr>
</tbody>
</table>
## Q2/1H 2020 Group Financial Highlights

<table>
<thead>
<tr>
<th></th>
<th>Q2 2020</th>
<th>Q2 2020</th>
<th>1H 2020</th>
<th>1H 2020</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>YoY</td>
<td>QoQ</td>
<td>YoY</td>
<td>HoH</td>
</tr>
<tr>
<td><strong>Bookings (USD)</strong></td>
<td>472m</td>
<td>-21.6%</td>
<td>1,141m</td>
<td>+7.4%</td>
</tr>
<tr>
<td></td>
<td></td>
<td>-29.4%</td>
<td></td>
<td>+19.0%</td>
</tr>
<tr>
<td><strong>Revenue (USD)</strong></td>
<td>557m</td>
<td>+19.5%</td>
<td>992m</td>
<td>+5.9%</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+27.8%</td>
<td></td>
<td>-10.5%</td>
</tr>
<tr>
<td><strong>Gross Margin</strong></td>
<td>35.2%</td>
<td>-54 bps</td>
<td>34.5%</td>
<td>-34 bps</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+169 bps</td>
<td></td>
<td>-29 bps</td>
</tr>
<tr>
<td><strong>EBIT (HKD)</strong></td>
<td>457m</td>
<td>+107.4%</td>
<td>581m</td>
<td>+20.0%</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+269.6%</td>
<td></td>
<td>-14.9%</td>
</tr>
<tr>
<td><strong>Net Profit (HKD)</strong></td>
<td>365m</td>
<td>+421.8%</td>
<td>391m</td>
<td>+119.2%</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+1,341.5%</td>
<td></td>
<td>-12.0%</td>
</tr>
<tr>
<td><strong>Net Profit Margin</strong></td>
<td>8.5%</td>
<td>+652 bps</td>
<td>5.1%</td>
<td>+262 bps</td>
</tr>
<tr>
<td></td>
<td></td>
<td>+771 bps</td>
<td></td>
<td>-9 bps</td>
</tr>
</tbody>
</table>
Q2/1H 2020 Segment Results – Semiconductor Solutions

<table>
<thead>
<tr>
<th></th>
<th>Amount</th>
<th>YoY</th>
<th>QoQ</th>
<th>Amount</th>
<th>YoY</th>
<th>HoH</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bookings (USD)</td>
<td>227m</td>
<td>-8.1%</td>
<td>-26.7%</td>
<td>537m</td>
<td>+14.2%</td>
<td>+21.7%</td>
</tr>
<tr>
<td>Billings (USD)</td>
<td>279m</td>
<td>+33.8%</td>
<td>+43.0%</td>
<td>473m</td>
<td>+16.6%</td>
<td>-4.5%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>42.9%</td>
<td>+211 bps</td>
<td>+162 bps</td>
<td>42.2%</td>
<td>+219 bps</td>
<td>+16 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>336m</td>
<td>+404.3%</td>
<td>+297.2%</td>
<td>420m</td>
<td>+251.8%</td>
<td>+17.6%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>15.5%</td>
<td>+1,140 bps</td>
<td>+993 bps</td>
<td>11.4%</td>
<td>+764 bps</td>
<td>+215 bps</td>
</tr>
</tbody>
</table>
## Q2/1H 2020 Segment Results – Materials

<table>
<thead>
<tr>
<th></th>
<th>Q2 2020</th>
<th></th>
<th>1H 2020</th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Amount</td>
<td>YoY</td>
<td>QoQ</td>
<td>Amount</td>
</tr>
<tr>
<td>Bookings (USD)</td>
<td>78m</td>
<td>+32.7%</td>
<td>-11.8%</td>
<td>167m</td>
</tr>
<tr>
<td>Billings (USD)</td>
<td>74m</td>
<td>+28.2%</td>
<td>+43.2%</td>
<td>126m</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>16.9%</td>
<td>+546 bps</td>
<td>+838 bps</td>
<td>13.5%</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>58m</td>
<td>+193.7%</td>
<td>+266.6%</td>
<td>74m</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>10.1%</td>
<td>+569 bps</td>
<td>+616 bps</td>
<td>7.6%</td>
</tr>
</tbody>
</table>
# Q2/1H 2020 Segment Results – SMT Solutions

## Financial Review

<table>
<thead>
<tr>
<th></th>
<th>Q2 2020</th>
<th>1H 2020</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>Amount</td>
<td>YoY</td>
</tr>
<tr>
<td>Bookings (USD)</td>
<td>167m</td>
<td>-43.7%</td>
</tr>
<tr>
<td>Billings (USD)</td>
<td>204m</td>
<td>+2.2%</td>
</tr>
<tr>
<td>Gross Margin</td>
<td>31.3%</td>
<td>-616 bps</td>
</tr>
<tr>
<td>Segment Profit (HKD)</td>
<td>159m</td>
<td>-24.0%</td>
</tr>
<tr>
<td>Segment Profit Margin</td>
<td>10.0%</td>
<td>-346 bps</td>
</tr>
</tbody>
</table>
Free Cash Flow and Capital Investment

Free Cash Flow (HK$ m)

- 2013: 418
- 2014: 1,108
- 2015: 605
- 2016: 1,604
- 2017: 437
- 2018: 806
- 2019: 2,116
- 1H 2020: 1,095

Capital Investment (US$ m)

- 2015: 72
- 2016: 55
- 2017: 82
- 2018: 104
- 2019: 88
- 2019B: 90
- 1H 2020: 15
- 2020B: 82
- 2020E: 80

D&A (excl. ROU/lease assets)
Financial Metrics

Return on Invested Capital (ROIC)

Return on Equity (ROE)
Working Capital Management

- **Working Capital**
  - HKD millions
  - Years: 2014-2019, 1H 2020

- **Cash Conversion Cycle (Days)**
  - Days: 0-300
  - Years: 2014-2019, 1H 2020

- **Accounts Receivable**
  - HKD millions
  - Years: 2014-2019, 1H 2020

- **Inventory**
  - HKD millions
  - Years: 2014-2019, 1H 2020

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**Financial Review**

- ASM Pacific Technology
ASM Pacific Technology

ENABLING THE DIGITAL WORLD